



Docket No.: M4065.0227/P227

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Tongbi Jiang, et al.

Application No.: 09/652,216

Group Art Unit: 2829

Filed: August 30, 2000

Examiner: E. Pert

For: METHOD AND APPARATUS FOR  
REDUCING SUBSTRATE BIAS VOLTAGE  
DROP

AMENDMENT

**Box Non-Fee Amendment**  
Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the Office Action dated August 30, 2002 (Paper No. 10), please amend the above-identified U.S. Patent application as follows:

In the Claims

Please cancel claims 92 and 94.

Please amend claims 1, 66, 96-99, and 101-104 to read as follows:

1. (Amended) A semiconductor device comprising:  
a semiconductor substrate;  
at least one electrical element circuit fabricated on an upper side of said  
substrate;